

4-20mA CURRENT LOOP TRANSMITTERS

FEATURES

- LOW QUIESCENT CURRENT: 200µA
- 5V REGULATOR FOR EXTERNAL CIRCUITS
- V_{REF} FOR SENSOR EXCITATION:
XTR115: 2.5V
XTR116: 4.096V
- LOW SPAN ERROR: 0.05%
- LOW NONLINEARITY ERROR: 0.003%
- WIDE LOOP SUPPLY RANGE: 7.5V to 36V
- SO-8 PACKAGE

DESCRIPTION

The XTR115 and XTR116 are precision current output converters designed to transmit analog 4-to-20mA signals over an industry standard current loop. They provide accurate current scaling and output current limit functions.

The on-chip voltage regulator (5V) can be used to power external circuitry. A precision on-chip V_{REF} (2.5V for XTR115 and 4.096V for XTR116) can be

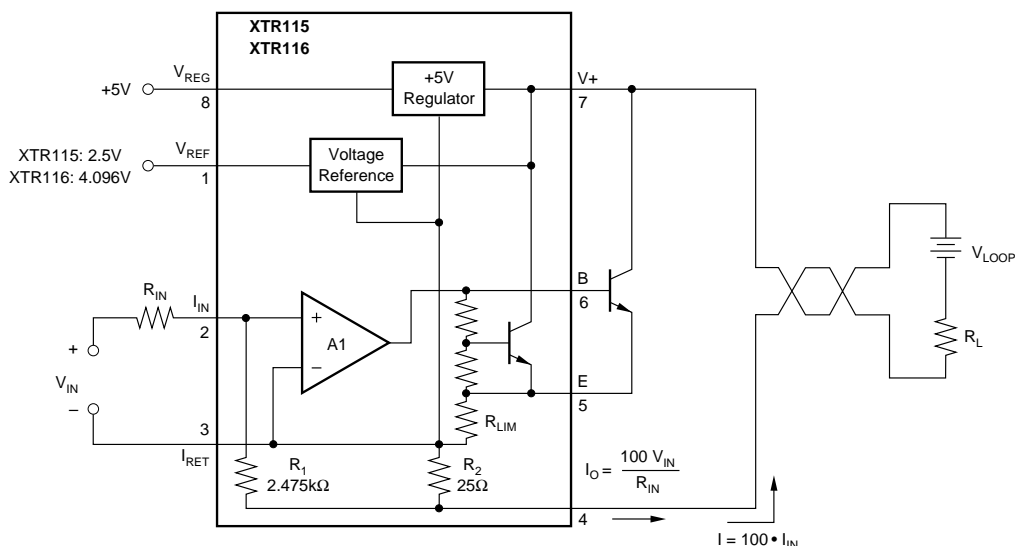
APPLICATIONS

- 2-WIRE, 4-20mA CURRENT LOOP TRANSMITTER
- SMART TRANSMITTER
- INDUSTRIAL PROCESS CONTROL
- TEST SYSTEMS
- COMPATIBLE WITH HART MODEM
- CURRENT AMPLIFIER
- VOLTAGE-TO-CURRENT AMPLIFIER

used for offsetting or to excite transducers. A current return pin (I_{RET}) senses any current used in external circuitry to assure an accurate control of the output current.

The XTR115 is a fundamental building block of smart sensors using 4-to-20mA current transmission.

The XTR115 and XTR116 are specified for operation over the extended industrial temperature range, -40°C to $+85^{\circ}\text{C}$.



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SPECIFICATIONS

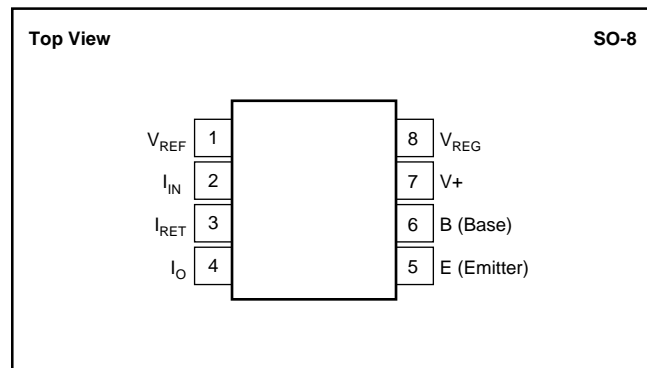
At $T_A = +25^\circ\text{C}$, $V_+ = 24\text{V}$, $R_{IN} = 20\text{k}\Omega$, and TIP29C external transistor, unless otherwise noted.

| PARAMETER | CONDITIONS | XTR115U XTR116U | | | XTR115UA XTR116UA | | | UNITS |
|--|--|--------------------|--------------------------|------------|----------------------|-----|------------|------------------------------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | |
| OUTPUT | | | | | | | | |
| Output Current Equation | I_O | | $I_O = I_{IN} \cdot 100$ | | | | | |
| Output Current, Linear Range | | 0.25 | | 25 | * | * | * | mA |
| Over-Scale Limit | I_{LIM} | | 32 | | | * | * | mA |
| Under-Scale Limit | I_{MIN} | | 0.2 | 0.25 | | * | * | mA |
| | $I_{REG} = 0, I_{REF} = 0$ | | | | | | | |
| SPAN | | | | | | | | |
| Span (Current Gain) | S | | 100 | | | * | * | A/A |
| Error ⁽¹⁾ | | | ± 0.05 | ± 0.2 | | * | ± 0.4 | % |
| vs Temperature | | | ± 3 | ± 20 | | * | * | ppm/ $^\circ\text{C}$ |
| Nonlinearity | | | ± 0.003 | ± 0.01 | | * | ± 0.02 | % |
| | $I_{IN} = 250\mu\text{A}$ to 25mA $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ $I_{IN} = 250\mu\text{A}$ to 25mA | | | | | | | |
| INPUT | | | | | | | | |
| Offset Voltage (Op Amp) | V_{OS} | | ± 100 | ± 250 | | * | ± 500 | μV |
| vs Temperature | | | ± 0.7 | ± 3 | | * | ± 6 | $\mu\text{V}/^\circ\text{C}$ |
| vs Supply Voltage, V_+ | | | ± 0.1 | ± 2 | | * | * | $\mu\text{V}/\text{V}$ |
| Bias Current | I_B | | -35 | | | * | * | nA |
| vs Temperature | | | 150 | | | * | * | pA/ $^\circ\text{C}$ |
| Noise: 0.1Hz to 10Hz | e_n | | 0.6 | | | * | * | $\mu\text{Vp-p}$ |
| | $I_{IN} = 40\mu\text{A}$ $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ $V_+ = 7.5\text{V}$ to 36V | | | | | | | |
| DYNAMIC RESPONSE | | | | | | | | |
| Small Signal Bandwidth | $C_{LOOP} = 0, R_L = 0$ | | 380 | | | * | | kHz |
| Slew Rate | | | 3.2 | | | * | | mA/ μs |
| $V_{REF}^{(2)}$ | | | | | | | | |
| XTR115 | | | 2.5 | | | * | | V |
| XTR116 | | | 4.096 | | | * | | V |
| Voltage Accuracy | | | ± 0.05 | ± 0.25 | | * | ± 0.5 | % |
| vs Temperature | | | ± 20 | ± 35 | | * | ± 75 | ppm/ $^\circ\text{C}$ |
| vs Supply Voltage, V_+ | | | ± 1 | ± 10 | | * | * | ppm/V |
| vs Load | | | ± 100 | | | * | * | ppm/mA |
| Noise: 0.1Hz to 10Hz | | | 10 | | | * | * | $\mu\text{Vp-p}$ |
| Short-Circuit Current | | | 16 | | | * | * | mA |
| | $I_{REF} = 0$ $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ $V_+ = 7.5\text{V}$ to 36V $I_{REF} = 0\text{mA}$ to 2.5mA | | | | | | | |
| $V_{REG}^{(2)}$ | | | | | | | | |
| Voltage | | | 5 | | | * | * | V |
| Voltage Accuracy | | | ± 0.05 | ± 0.1 | | * | * | V |
| vs Temperature | | | ± 0.1 | | | * | * | mV/ $^\circ\text{C}$ |
| vs Supply Voltage, V_+ | | | 1 | | | * | * | mV/V |
| vs Output Current | | | See Typical Curves | | | * | * | mA |
| Short-Circuit Current | | | 12 | | | * | * | mA |
| | $I_{REG} = 0$ $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ $V_+ = 7.5\text{V}$ to 36V | | | | | | | |
| POWER SUPPLY | V_+ | | | | | | | |
| Specified | | | +24 | | | * | * | V |
| Voltage Range | | +7.5 | | +36 | * | | * | V |
| Quiescent Current | | | 200 | 250 | | * | * | μA |
| Over Temperature, -40°C to $+85^\circ\text{C}$ | | | 240 | 300 | | * | * | μA |
| TEMPERATURE RANGE | | | | | | | | |
| Specification | | -40 | | +85 | * | | * | $^\circ\text{C}$ |
| Operating | | -55 | | +125 | * | | * | $^\circ\text{C}$ |
| Storage | | -55 | | +125 | * | | * | $^\circ\text{C}$ |
| Thermal Resistance | θ_{JA} | | 150 | | | * | * | $^\circ\text{C}/\text{W}$ |

* Specifications the same as XTR115U and XTR116U.

NOTES: (1) Does not include initial error or TCR of R_{IN} . (2) Voltage measured with respect to I_{RET} pin.

PIN CONFIGURATION



PACKAGE/ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| | |
|--|-----------------|
| Power Supply, $V+$ (referenced to I_O pin) | 40V |
| Input Voltage (referenced to I_{RET} pin) | 0V to $V+$ |
| Output Current Limit | Continuous |
| V_{REG} , Short-Circuit | Continuous |
| V_{REF} , Short-Circuit | Continuous |
| Operating Temperature | -55°C to +125°C |
| Storage Temperature Range | -55°C to +125°C |
| Lead Temperature (soldering, 10s) | +300°C |
| Junction Temperature | +165°C |

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability.



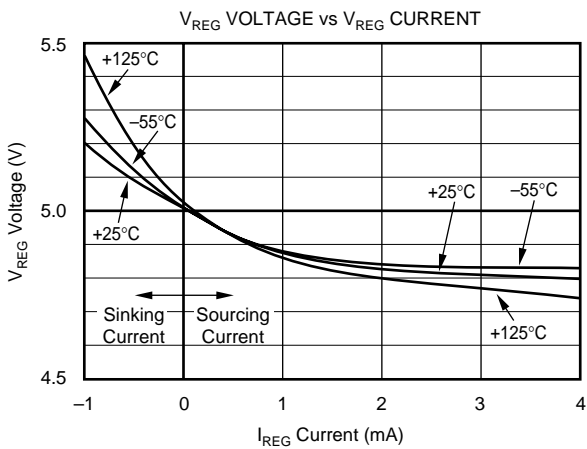
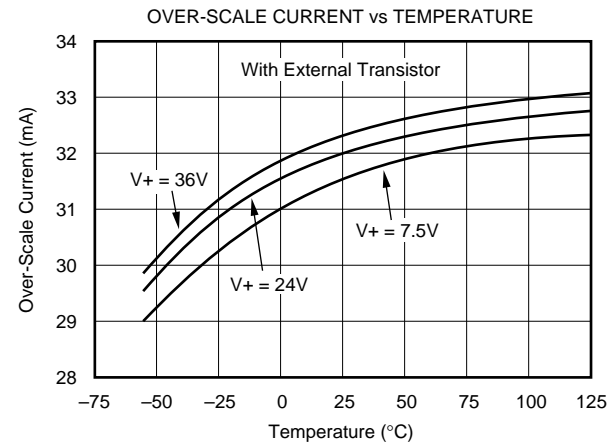
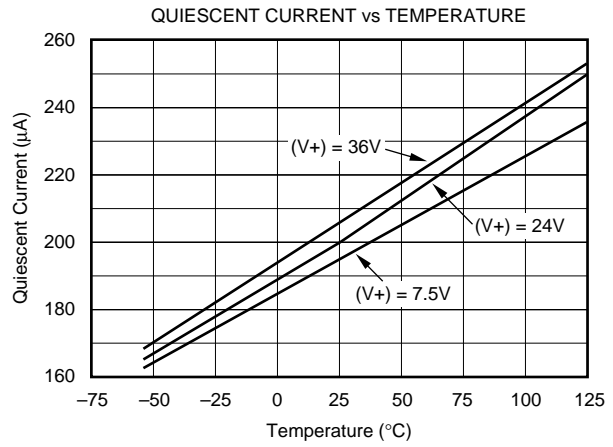
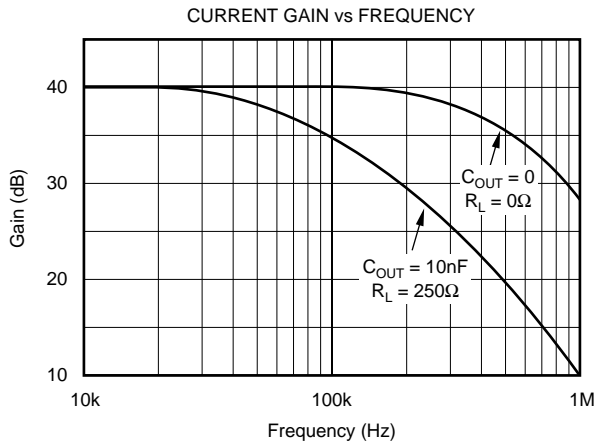
ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

TYPICAL PERFORMANCE CURVES

At $T_A = +25^\circ\text{C}$, $V_+ = 24\text{V}$, $R_{IN} = 20\text{k}\Omega$, and TIP29C external transistor, unless otherwise noted.



APPLICATIONS INFORMATION

The XTR115 and XTR116 are identical devices except for the reference voltage output, pin 1. This voltage is available for external circuitry and is not used internally. Further discussions that apply to both devices will refer to the “XTR115/6.”

Figure 1 shows basic circuit connections with representative simplified input circuitry. The XTR115/6 is a two-wire current transmitter. Its input signal (pin 2) controls the output current. A portion of this current flows into the V+ power supply, pin 7. The remaining current flows in Q1. External input circuitry connected to the XTR115/6 can be powered from V_{REG} or V_{REF}. Current drawn from these terminals must be returned to I_{RET}, pin 3. This I_{RET} pin is a “local ground” for input circuitry driving the XTR115/6.

The XTR115/6 is a current-input device with a gain of 100. A current flowing into pin 2 produces I_O = 100 • I_{IN}. The input voltage at the I_{IN} pin is zero (referred to the I_{RET} pin). A voltage input is created with an external input resistor, as shown. Common full-scale input voltages range from 1V

and upward. Full-scale inputs greater than 0.5V are recommended to minimize the effect of offset voltage and drift of A1.

EXTERNAL TRANSISTOR

The external transistor, Q1, conducts the majority of the full-scale output current. Power dissipation in this transistor can approach 0.8W with high loop voltage (40V) and 20mA output current. The XTR115/6 is designed to use an external transistor to avoid on-chip thermal-induced errors. Heat produced by Q1 will still cause ambient temperature changes that can affect the XTR115/6. To minimize these effects, locate Q1 away from sensitive analog circuitry, including XTR115/6. Mount Q1 so that heat is conducted to the outside of the transducer housing.

The XTR115/6 is designed to use virtually any NPN transistor with sufficient voltage, current and power rating. Case style and thermal mounting considerations often influence the choice for any given application. Several possible choices are listed in Figure 1. A MOSFET transistor will not improve the accuracy of the XTR115/6 and is not recommended.



FIGURE 1. Basic Circuit Connections.

MINIMUM-SCALE CURRENT

The quiescent current of the XTR115/6 (typically 200 μ A) is the lower limit of its output current. Zero input current ($I_{IN} = 0$) will produce an I_O equal to the quiescent current. Output current will not begin to increase until $I_{IN} > I_Q/100$. Current drawn from V_{REF} or V_{REG} will add to this minimum output current. This means that more than 3.7mA is available to power external circuitry while still allowing the output current to go below 4mA.

OFFSETTING THE INPUT

A low scale of 4mA is produced by creating a 40 μ A input current. This can be created with the proper value resistor from V_{REF} (Figure 2), or by generating offset in the input drive circuitry.

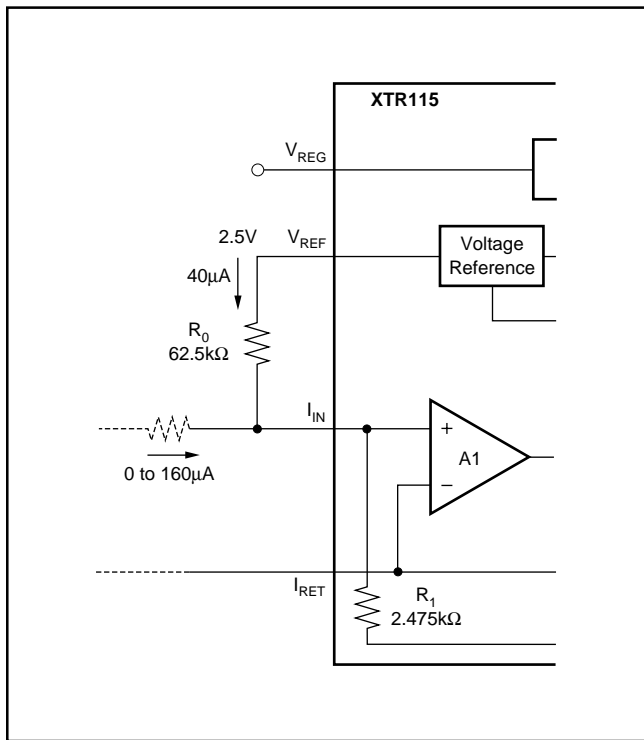


FIGURE 2. Creating Low-Scale Offset.

MAXIMUM OUTPUT CURRENT

The XTR115/6 provides accurate, linear output up to 25mA. Internal circuitry limits the output current to approximately 32mA to protect the transmitter and loop power/measurement circuitry.

It is possible to extend the output current range of the XTR115/6 by connecting an external resistor from pin 3 to pin 5, to change the current limit value. Since all output current must flow through internal resistors, it is possible to damage with excessive current. Output currents greater than 45mA may cause permanent damage.

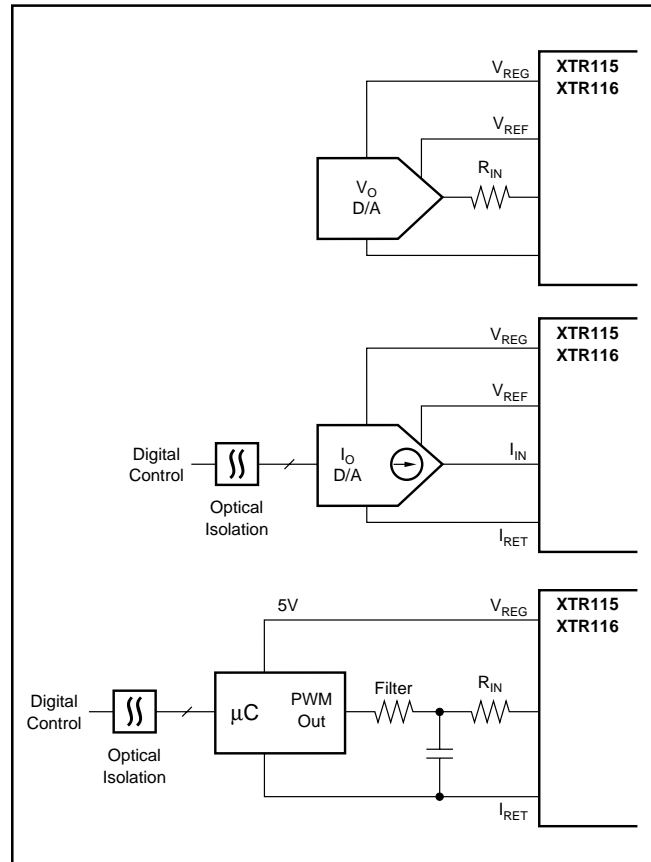


FIGURE 3. Digital Control Methods.

REVERSE-VOLTAGE PROTECTION

The XTR115/6 low compliance voltage rating (7.5V) permits the use of various voltage protection methods without compromising operating range. Figure 4 shows a diode bridge circuit which allows normal operation even when the voltage connection lines are reversed. The bridge causes a two diode drop (approximately 1.4V) loss in loop supply voltage. This results in a compliance voltage of approximately 9V—satisfactory for most applications. A diode can be inserted in series with the loop supply voltage and the V+ pin to protect against reverse output connection lines with only a 0.7V loss in loop supply voltage.

OVER-VOLTAGE SURGE PROTECTION

Remote connections to current transmitters can sometimes be subjected to voltage surges. It is prudent to limit the maximum surge voltage applied to the XTR115/6 to as low as practical. Various zener diode and surge clamping diodes are specially designed for this purpose. Select a clamp diode with as low a voltage rating as possible for best protection. For example, a 36V protection diode will assure proper transmitter operation at normal loop voltages, yet will provide an appropriate level of protection against voltage surges. Characterization tests on several production lots showed no damage with loop supply voltages up to 65V.

Most surge protection zener diodes have a diode characteristic in the forward direction that will conduct excessive current, possibly damaging receiving-side circuitry if the loop connections are reversed. If a surge protection diode is used, a series diode or diode bridge should be used for protection against reversed connections.

RADIO FREQUENCY INTERFERENCE

The long wire lengths of current loops invite radio frequency interference. RF can be rectified by the input circuitry of the XTR115/6 or preceding circuitry. This generally appears as an unstable output current that varies with the position of loop supply or input wiring.

Interference may also enter at the input terminals. For integrated transmitter assemblies with short connection to the sensor, the interference more likely comes from the current loop connections.

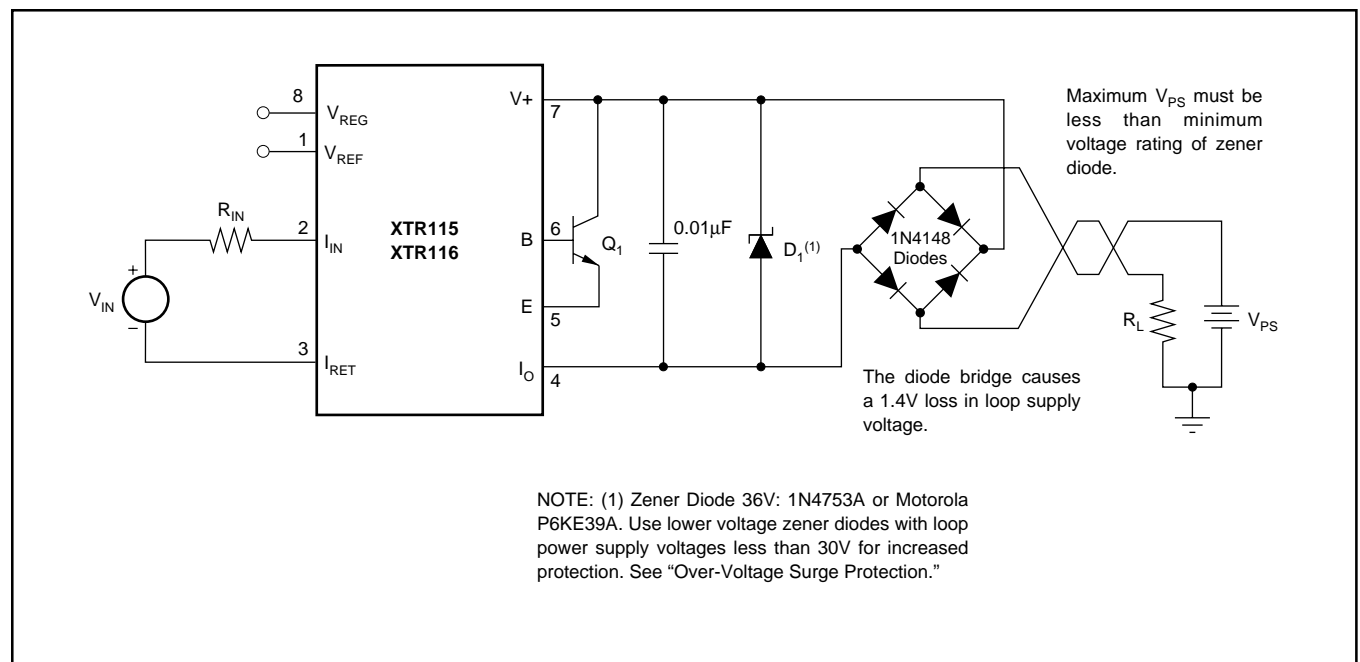


FIGURE 4. Reverse Voltage Operation and Over-Voltage Surge Protection.

If capacitive loading must be placed on the V_{REF} pin, one of the compensation schemes shown below must be used to ensure stable operation. Values of capacitance must remain within the given ranges.



NOTE: (1) Required compensation components.

FIGURE 5. Stable Operation with Capacitive Load on V_{REF}

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| XTR115U | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U | Samples |
| XTR115U/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U | Samples |
| XTR115U/2K5E4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U | Samples |
| XTR115UA | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U A | Samples |
| XTR115UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U A | Samples |
| XTR115UA/2K5E4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U A | Samples |
| XTR115UG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 115U | Samples |
| XTR116U | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U | Samples |
| XTR116U/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U | Samples |
| XTR116U/2K5G4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U | Samples |
| XTR116UA | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U A | Samples |
| XTR116UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U A | Samples |
| XTR116UA/2K5E4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U A | Samples |
| XTR116UAE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|----------------|
| XTR116UG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | XTR 116U | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| XTR115U/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| XTR115UA/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| XTR116U/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| XTR115U/2K5 | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| XTR115UA/2K5 | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| XTR116U/2K5 | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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